

Title (en)  
ELECTRIC COMPONENT IN INTEGRATED CIRCUIT FORM FOR HOT INSERTION IN A SUBSTRATE AND METHODS FOR MANUFACTURING SAME

Title (de)  
ELEKTRONISCHE KOMPONENTE IN DER GESTALT EINER INTEGRIERTEN SCHALTUNG ZUM HEISSEN MONTIEREN IN EINEM SUBSTRAT UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)  
COMPOSANT ELECTRIQUE SOUS FORME DE CIRCUIT INTEGRE POUR INSERTION A CHAUD DANS UN SUBSTRAT ET PROCEDES POUR SA FABRICATION

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Application  
**EP 97921930 A 19970505**

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Abstract (en)  
[origin: WO9742657A1] The invention discloses an electronic component in the form of a circuit (10, 13) on a chip (1), comprising at least on its inactive surface (4) a thermoplastic or thermosetting heat-reactivable adhesive coating (5).

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**H01L 23/495**; **H01L 21/58**

IPC 8 full level  
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